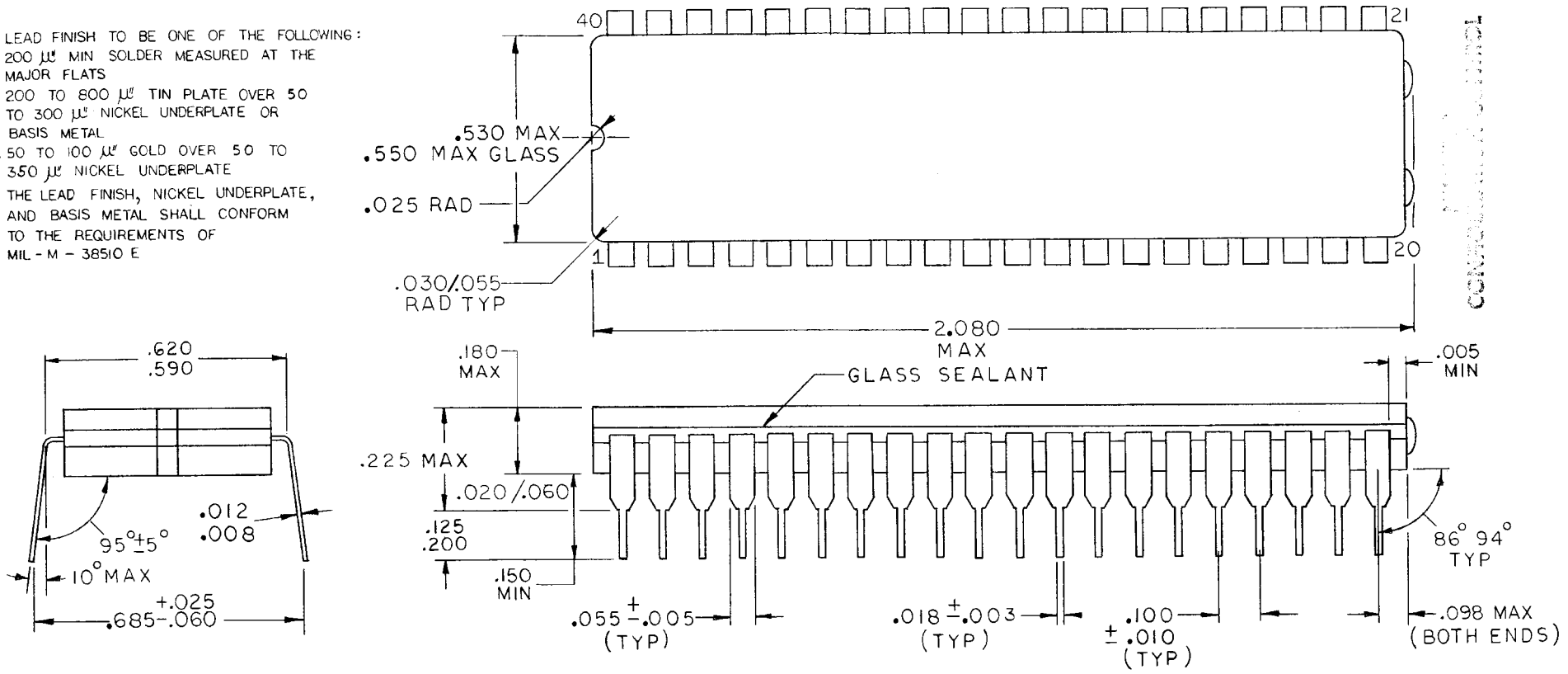


					REVISIONS								
REV.	SHEET	DESCRIPTION	E.C.O.	DATE	APPROVED								
B	1	J40 A WAS J40 B	D	7-11-77	F.Z.	⊕	1	NEW DW'G	01875	8-25-76			
C	1	ADDED 95° ± 5° AND 86° 94° TYP	D	3-29-79	for Weber	A	1	REDRAWN	02295	3-1-77			
D	1	2.080 WAS 2.060, ADDED .030/.055 RAD TYP	D	6-27-79		E	1	ADDED 10° MAX	4167	8-17-79			
F	1	.685 ± .025 - .060, .210, .055 ± .005, .620, .590 WERE .685 ± .05, .206, .060 ± .025, .622, .590, REM. 175, .025/.005	D	9-25-79									

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
- 200 μs MIN SOLDER MEASURED AT THE MAJOR FLATS
  - 200 TO 800 μs TIN PLATE OVER 50 TO 300 μs NICKEL UNDERPLATE OR BASIS METAL
  - 50 TO 100 μs GOLD OVER 50 TO 350 μs NICKEL UNDERPLATE
- THE LEAD FINISH, NICKEL UNDERPLATE, AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL - M - 38510 E



K	1	REVISED LEAD FINISH NOTES 1+2 AND ADDED BUMPERS.	D8473	5-24-83	J. Maciel
J	1	ADDED .020/.060, .125/.200, .098 MAX, .150 MIN, .005 MIN WERE .020/.070, .125 MIN AND .050 MIN REVISED LEAD FINISH	D7053	6-15-82	JTE
H	1	ADDED .180 MAX, .225 WAS .200	D6984	5-12-82	J. Maciel
G	1	ADDED .020/.570	D4416	11-9-79	J. Maciel

<b>COMPANY PRIVATE</b>				 <b>National Semiconductor Corporation</b> 2900 Semiconductor Drive, Santa Clara, Calif. 95051	
DRAWN:	DATE:	APPROVED:	DATE:	40 LEAD, CERDIP	
J. MACIEL	3-1-77	J. Maciel	3-1-77		
CHECKED:	DATE:	APPROVED:	DATE:	B MKT-J40A	
ENGINEER:	DATE:	RELEASED:	DATE:	SHEET 1 OF 1	
				REV. K	